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MT29C4G48MAYBBAKS-48 IT

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Data Sheets (1)

[Data Sheet](#)

137-Ball 4Gb NAND Flash with 2Gb LPDDR MCP Data Sheet

J4Q2; MT29C4G48MAYBBAKS-48 IT, MT29C4G48MAZBBAKS-48 IT, MT29C4G48MAYBBAHK-48 AIT

File Type: PDF

Updated: 11/2014

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Automotive

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Multichip Packages

NAND LPDDR

NAND-Based MCP

Specs

Orderable Parts for: MT29C4G48MAYBBAKS-48 IT [SEE ALL NAND-BASED MCP PARTS](#)

	Status	Media	FBGA Code	SPD Data	Chipset Validation	PLP	Start Date	Alternative Part
MT29C4G48MAYBBAKS-48 IT	Production	N/A	JWB09	N/A	N/A	No		N/A

Detailed Specifications

Part Status Code	Production	NAND Density	4Gb	DRAM Type	LPDDR	DRAM Density	2Gb
Bus Width	x8	Secondary Bus Width	x16	RoHS	Yes	Voltage	1.7V-1.9V
Package	VFBGA	Pin Count	137-ball	Clock Rate	208 MHz	Operating Temp	-40C to +85C

Sim Models & Software

Sim Models

IBIS



IBIS_J4Q2_FBGA130, FBGA137, FBGA168 (ZIP)

Multichip Packages
NAND LPDDR

4Gb: x8, x16 NAND Flash with 2Gb: x32 LPDDR MCP

File Type: ZIP

Updated: 03/15/2016

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RoHS Certificates

RoHS Certificates

RoHS Certificate of Compliance (PDF)

MT29C4G48MAYBBAKS-48 IT

Part-specific certification of how this product meets the requirements of the current DIRECTIVE 2002/95/EC, a.k.a. Restriction of Hazardous Substances (RoHS) Directive.

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RoHS Certificates

China RoHS Certificate (PDF)

MT29C4G48MAYBBAKS-48 IT

Part-specific certification as required by China's Management Methods for Controlling Pollution by Electronic Information Products.

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Documentation & Support

[See All NAND-Based MCP Documentation](#)

Technical Notes

SEARCH (2) NAND-BASED MCP TECHNICAL NOTES

Technical Notes

TN-00-01: Moisture Sensitivity of Plastic Packages (PDF)

(TN-00-01) This technical note describes shipping procedures for preventing memory devices from absorbing moisture and recommendations for baking devices exposed to excessive moisture.

[DDR SDRAM](#)
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Technical Notes

TN-10-08: Thermal Implications for LPDDR Die Stacks (PDF)

(TN-10-08) This technical note presents a case study of a handset simulation in which an LPDRAM is stacked on an application processor (PoP) and the resulting thermal-profile modeling. This note also explains how thermal detection features included in LPDDR and LPDDR2 can be used to...

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Customer Service Note

Customer Service Note

Customer Service Note

Micron Component and Module Packaging (PDF)

(CSN-16) Explanation of Micron packaging labels and procedures.

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Customer Service Note

PoP User Guide (PDF)

(CSN-34) Provides several well-established guidelines for package-on-package (PoP) semiconductor package design and assembly, which requires unique considerations in both the up-front design and the manufacturing process.

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[SEARCH \(2\) NAND-BASED MCP CUSTOMER SERVICE NOTE](#)

Parts with the same Data Sheet (2)

MT29C4G48MAYBBAKS-48 IT (Current)		MT29C4G48MAZBBAKS-48 IT	MT29C4G48MAYBBAHK-48 A IT
Part Status Code	Production	Production	Production
NAND Density	4Gb	4Gb	4Gb
DRAM Type	LPDDR	LPDDR	LPDDR
DRAM Density	2Gb	2Gb	2Gb
Bus Width	x8	x16	x8
Secondary Bus Width	x16	x32	x32
RoHS	Yes	Yes	Yes
Voltage	1.7V-1.9V	1.7V-1.9V	1.7V-1.9V
Package	VFBGA	VFBGA	VFBGA
Pin Count	137-ball	137-ball	137-ball
Clock Rate	208 MHz	208 MHz	208 MHz
Operating Temp	-40C to +85C	-40C to +85C	-40C to +85C

MT29C4G48MAYBBAKS-48 IT (Current)	
Part Status Code	Production
NAND Density	4Gb
DRAM Type	LPDDR
DRAM Density	2Gb
Bus Width	x8
Secondary Bus Width	x16
RoHS	Yes
Voltage	1.7V-1.9V
Package	VFBGA
Pin Count	137-ball
Clock Rate	208 MHz
Operating Temp	-40C to +85C

Where to Buy

Status	Media	FBGA Code	SPD Data	Chipset Validation	PLP	Start Date	Alternative Part
Production	N/A	JWB09	N/A	N/A	No		N/A

- OR - Check with Distributors

Your Region: Americas



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